

Abstract

Methods for attaching two wafers are presented along with devices resulting from such methods. In one illustrative embodiment, a first wafer is provided having pillars for conducting an electric signal. The wafer also includes an electronic device such as an inductor or capacitor that may in some instances consume relatively large amounts of space. The first wafer is bonded to a second wafer so that a circuit on the second wafer may be electrically connected to the electronic device of the first wafer.

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